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IEEE TRANSACTIONS ON ADVANCED PACKAGING

A Special Section on 3D Packaging

Manuscript Due Date: **July 1, 2003**

3D packaging provides major opportunities in both miniaturization and integration for advanced, portable electronic products. Some existing and emerging applications include sensors, memory modules, integrated RF microsystems, embedded processors, etc. More recent 3D solutions incorporating stacked package approaches offer solutions to market and business impediments plaguing MCM deployment for the past decade.

This **Special Section** in the *IEEE Transactions on Advanced Packaging* will survey state-of-the-art research in this challenging area. Topics of interest include but are not limited to:

- Design, fabrication, assembly, testing and reliability of 3D and stackable packages
- Technology developments such as hermetic, non-hermetic, vacuum or bio-compatible packaging
- Process control and other manufacturing challenges
- Characterization of materials and packages
- Innovative packaging and interconnect solutions for specific application environments

All manuscripts will be peer-reviewed and should be submitted electronically to IEEE's Manuscript Central on-line system at <http://cpmt-trans-ieee.manuscriptcentral.com/> before **July 1, 2003**. During submission, please **make a note that the manuscript is being submitted for the Special Section on 3D packaging**. To discuss a potential manuscript, please send an email to the Guest Editor (below). Each manuscript is expected to be fewer than 15 double-spaced pages (plus Figures and Tables); format should follow the IEEE requirements provided at www.cpmt.org/trans/transadvp-auth.html. Files may be submitted on the website as PDF, RTF, .ps, or .doc. Lead author should include full address, phone, FAX and Email address, to aid in communication. More details for preparation are provided on our website: http://www.cpmt.org/trans/style_guide.html.

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